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RIGHT ANGLE H2 RECEPTACLE NON-MAGNETIC SMT R107.003.087				
REEL OF 100			Series : UMP	
PACKAGING		SPECIFICATION		
Standard Unit	Other	PAQP-VOR-017		
100 'W' option	Contact us			
ELECTRICAL CHARACTERISTICS		<u>ENVIRONMENTAL</u>		
Frequency0-6VSWR1.05 +0,0300Insertion lossNARF leakage- (Voltage rating100Dielectric withstanding voltage350	Ω GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi Veff Maxi Veff mini MΩ mini	Operating tempe Hermetic seal Panel leakage	rature -40/+55 ° C NA Atm.cm3/s NA	
		OTHER CHARACTERISTICS		
		Assembly instruc	ction	
		Others :		
MECHANICAL CHARACTERISTICS		Magnetique field distorsion < to 0.5 ppm at 10mm at Bo=1.5 Tesla		
Axial force – Opposite end -	N mini N mini N.cm mini			
	N.cm N.cm			
Mating life100Weight0,0300	Cycles mini g			
		I		
<b>Issue :</b> 0739 A In the effort to improve our products, we reserve	the right to make cha	anges judged to be	🔀 RADIALL <sup>®</sup>	
necessary.			THE ALL	

#### TECHNICAL DATA SHEET 3 RIGHT ANGLE H2 RECEPTACLE NON-MAGNETIC SMT TYPE R107.003.087

**REEL OF 100** 

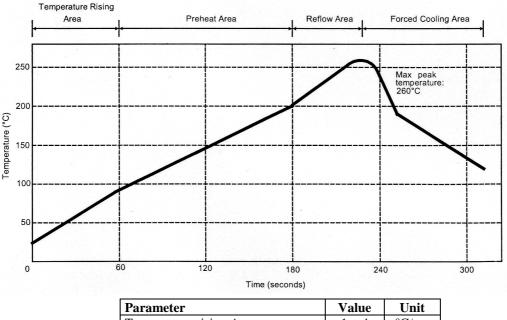
Series : UMP

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## SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

# NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec





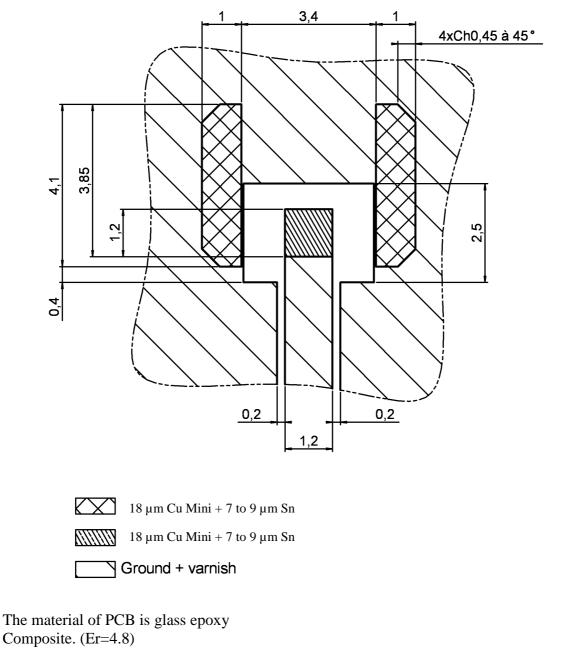
**REEL OF 100** 

Series : UMP

# **UMP SERIES INFORMATION**

## PCB

COPLANAR LINE Ground and signal are on the same side Thickness of PCB :1 mm



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